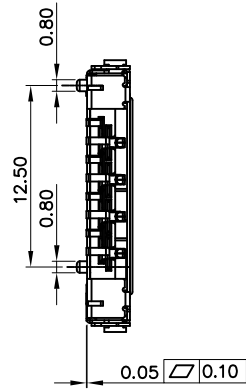
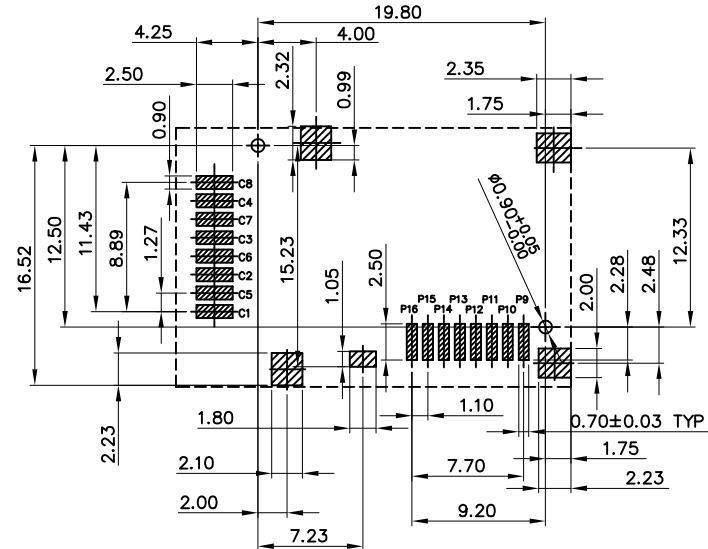
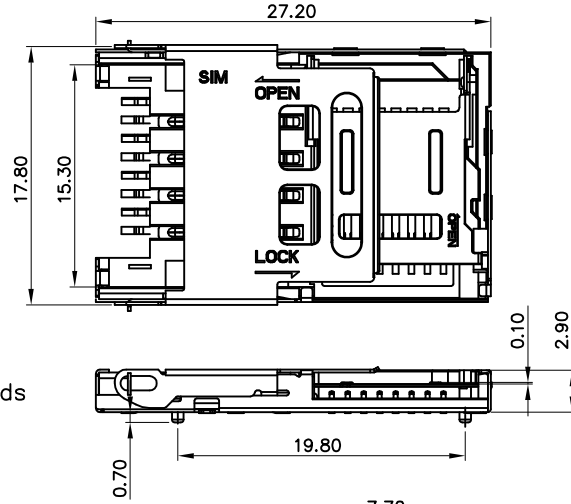


Global Connector Technology Ltd. - MES3055: 2 in 1 Combo Connector, Micro SD Memory Card/SIM Card, SMT, Hinged, 2.90mm Profile, With Locating Post

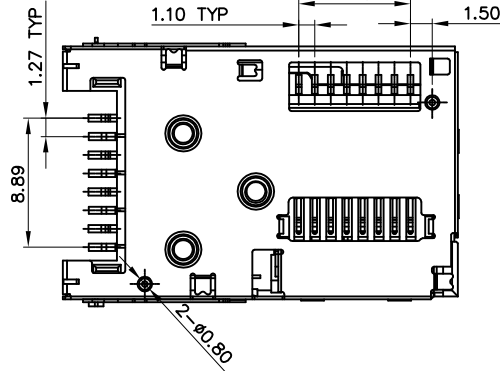
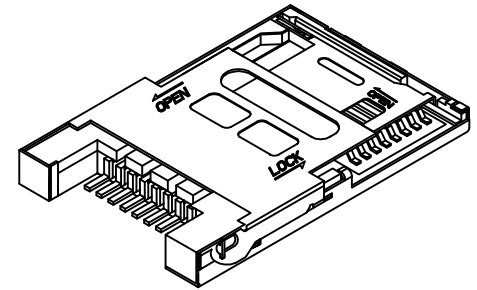


All Tails & Pads



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE: ±0.05
AS VIEWED FROM COMPONENT SIDE

- Solder Area
- Component Outline



D SPECIFICATION 规格:

MATERIAL 物料规格:
 PLASTIC HOUSING 塑胶外壳: HI-TEMP. THERMOPLASTIC UL94V-0 高温塑胶
 CONTACT TERMINAL 接触端子: PHOSPHOR BRONZE 磷青铜
 METALLIC SHELL 金属外壳: STAINLESS STEEL (SUS304R-H) 不锈钢
PLATING 电镀规格:
 CONTACT TERMINAL PLATING 接触端子部分电镀:
 UNDER-PLATING 底层电镀: NICKEL OVER ALL 全部镀镍
 CONTACT AREA 接触部分: GOLD 镀金
 SOLDERING AREA 焊接部分: MATTE TIN 镀雾锡
 METALLIC SHELL PLATING 金属外壳电镀:
 UNDER-PLATING 底层电镀: NICKEL OVER ALL 全部镀镍
 SOLDERING AREA 焊接部分: GOLD 镀金
 SOLDER TAIL CO-PLANARITY 焊接末端同平面度: 0.1MM MAX.

F ELECTRICAL 电气规格:

VOLTAGE RATING 电压额定值: 100 V AC/DC
 CURRENT RATING 电流额定值: 0.5A MAX
 OPERATING TEMPERATURE 工作温度: -25°C TO +70°C
 CONTACT RESISTANCE 接触电阻值: 30 mΩ MAX.
 INSULATION RESISTANCE 绝缘电阻值: 1000Ω MIN.
 DIELECTRIC WITHSTANDING VOLTAGE 耐电压: WITHSTAND 200 VAC FOR 1 MINUTE 能承受 200 VAC 1分钟

G MECHANICAL 机械规格:

DURABILITY 耐久性: 5000 CYCLES 5000 次插拔
 CONTACT RETENTION FORCE 接触保持力: 50GF/PIN MIN. OR 0.49N/PIN MIN.
 CONTACT NORMAL FORCE 垂直接触力:
 SIM: 80GF/PIN MIN. OR 0.784N/PIN MIN.
 MICRO SD: 40GF/PIN MIN. OR 0.392N/PIN MIN.
 INSERTION FORCE 插入力:
 SIM: 150GF/PIN MIN. OR 1.47N/PIN MIN.
 MICRO SD: 200GF/PIN MIN. OR 1.96N/PIN MIN.



Ordering Grid

MES3055 - 02 - 290 - 01 - A REQUEST SAMPLES AND QUOTATION

Packing Options
 A = Tape & Reel
 (Quantity per Reel: 350 pcs)

01 = With Locating Post
 02 = Without Switch

By	PKN	DMR	ASE	PN	AE
DETAIL	DRAWING RELEASE	ECN080717A	ECN080922A	STAGES OF OPERATION DRAWINGS ADDED TO PAGE 3	ADDITION TO SPECIFICATION
REV DATE	A 22/05/08	B 17/07/08	C 22/09/08	D 24/07/09	E 03/09/09



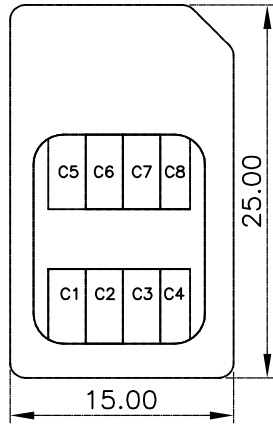
Tolerances (Except as noted)	Part Number:-	Date:-
Dimensions in mm	MES3055	22 MAY 08
X.X ± 0.35 X.X° ± 1°	Description:-	
X.XX ± 0.25 X.XX° ± 0.5°	2 IN 1 COMBO CONNECTOR, MICRO SD MEMORY CARD/SIM CARD, SMT, HINGED, 2.90MM PROFILE, WITH LOCATING POST	
X.XXX ± 0.150 X.XXX° ± 0.25°		
Third Angle Projection	© THIS DRAWING IS CONFIDENTIAL AND MUST NOT BE COPIED OR DISCLOSED WITHOUT WRITTEN CONSENT	

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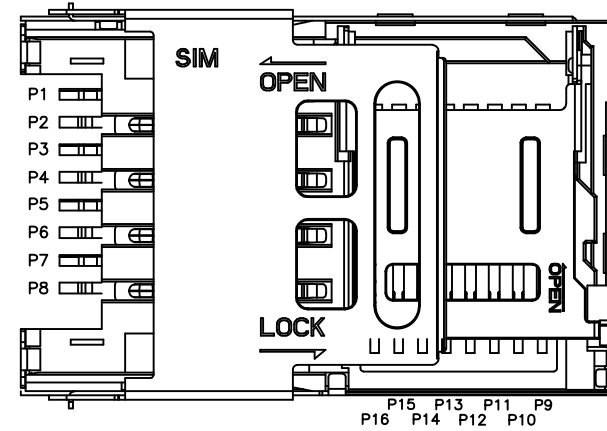
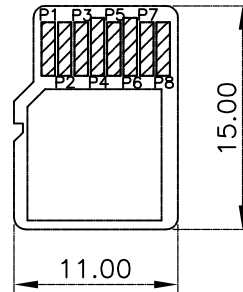
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Scale NTS	Revision E	Material See Note	Drawn by PKN	Sheet No. E & OE 1/5
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SIM CARD



MICRO SD CARD



SIM CARD PIN OUT		
Pin#	Name	Description
C1	VCC	+5v or 3.3v DC
C2	RST	Card Reset (Optional)
C3	CLK	Card Clock
C4	RFU	Reserved for Future Use
C5	GND	Ground
C6	VPP	+21v DC [Programming]
C7	I/O	In/Out [Data]
C8	RFU	Reserved for Future Use

Micro SD CARD PIN OUT		
Pin#	Name	Description
P1	DAT2	Data Bit 2
P2	CD/DAT3	Card Detect/Data Bit 3
P3	CMD	Command Line
P4	V _{DD}	Supply Voltage 2.7v/3.6v
P5	CLK	Clock
P6	V _{SS}	Ground
P7	DAT0	Data Bit 0
P8	DAT1	Data Bit 1

Combo Connector Pin Assignment:

PIN NO.	NAME	DESCRIPTION
P1	Sim Card C8 (AS)	Application Specific
P2	Sim Card C4 (AS)	Application Specific
P3	Sim Card C7 (I/O)	In/Out [Data]
P4	Sim Card C3 (CLK)	Card Clock
P5	Sim Card C6 (VPP)	+21v DC
P6	Sim Card C2 (RST)	Card Reset
P7	Sim Card C5 (GND)	Ground
P8	Sim Card C1 (VCC)	+5v or 3.3v DC
P9	Micro SD P1 (DAT2)	Data Bit 2
P10	Micro SD P2 (CD/DAT3)	Card Detect/Data Bit 3
P11	Micro SD P3 (CMD)	Command Line
P12	Micro SD P4 (VDD)	Supply Voltage 2.7v/3.6v
P13	Micro SD P5 (CLK)	Clock
P14	Micro SD P6 (VSS)	Ground
P15	Micro SD P7 (DAT0)	Data Bit 0
P16	Micro SD P8 (DAT2)	Data Bit 1

By	PKN	DMR	ASE	PN	AE
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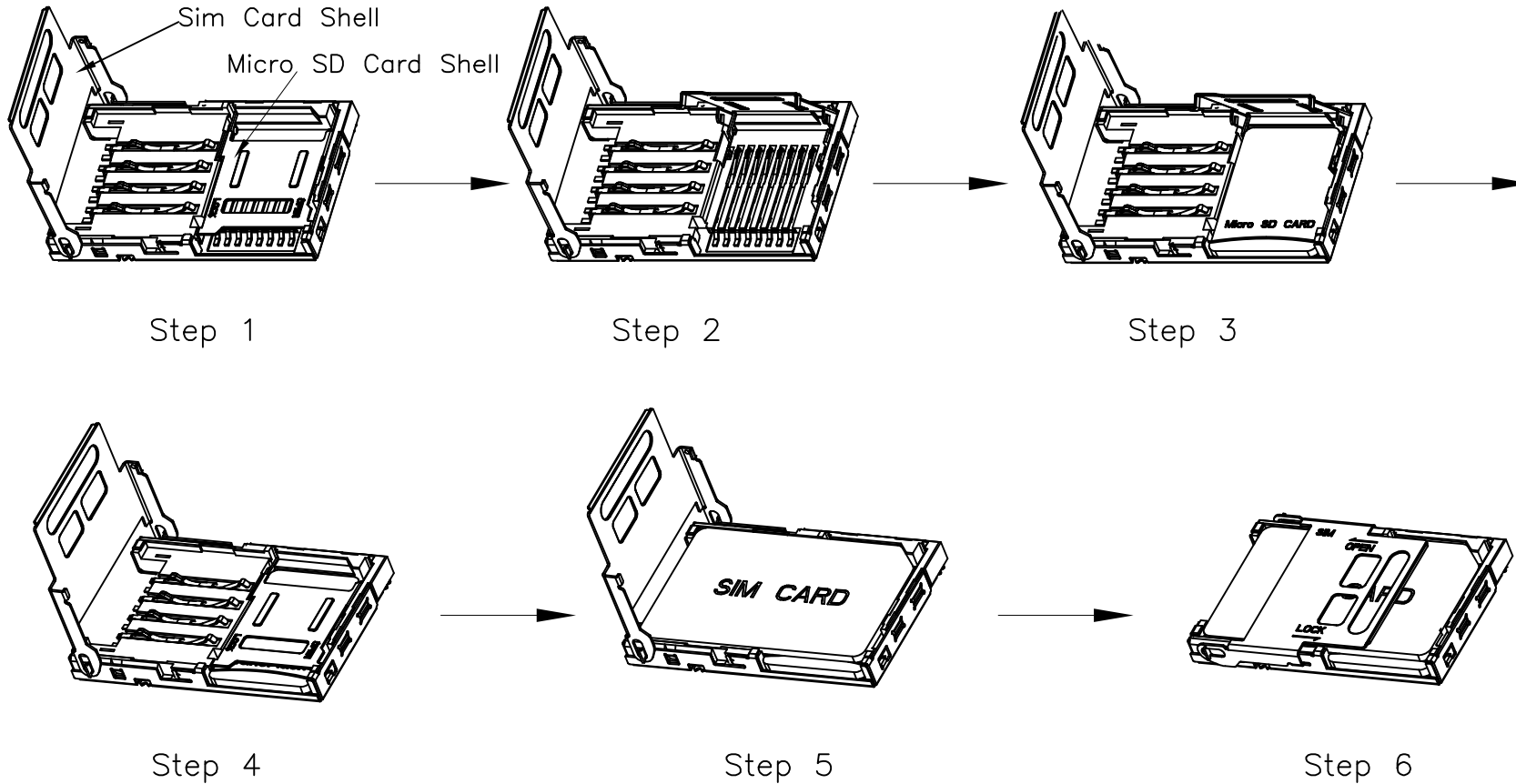


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Dimensions in mm	MES3055	22 MAY 08
X.X ± 0.35 X.° ± 1°	Description:-	
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X.XXX ± 0.150 X.XX° ± 0.25°		
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Scale NTS	Revision E	Material See Note	Drawn by PKN	Sheet No. 2/5
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STAGES OF OPERATION



1. Open the Hinge of the SIM Card Shell first.
2. Open the Hinge of the Micro SD Card Shell.
3. Insert the Micro SD Card.
4. Close the Hinge of the Micro SD Card Shell.
5. Insert the SIM Card.
6. Close the Hinge of the SIM Card Shell.

By	PKN	DMR	ASE	PN	AE
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REV	A	B	C	D	E
DATE	22/05/08	17/07/08	22/09/08	24/07/09	03/09/09

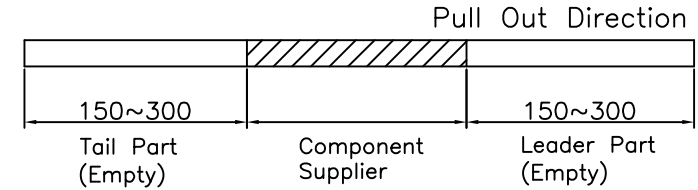
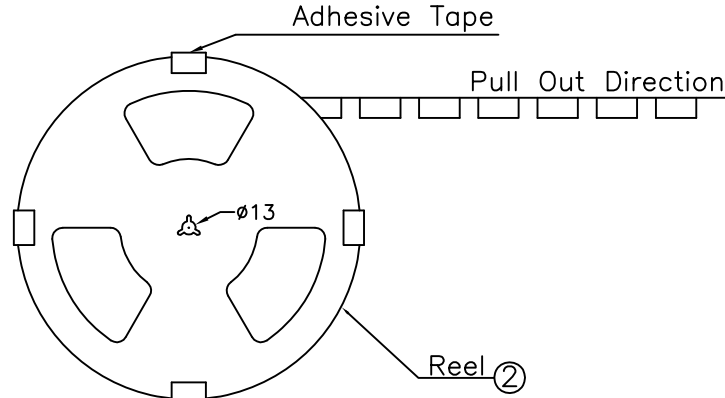
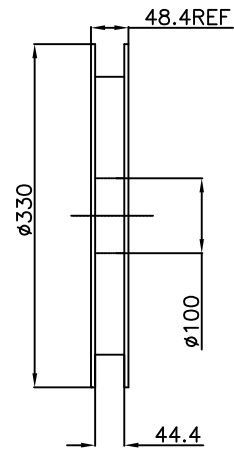


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Dimensions in mm		MES3055	22 MAY 08
X.X ± 0.35	X.° ± 1°	Description:-	
X.XX ± 0.25	X.X° ± 0.5°	2 IN 1 COMBO CONNECTOR, MICRO SD MEMORY CARD/SIM CARD, SMT, HINGED, 2.90MM PROFILE, WITH LOCATING POST	
X.XXX ± 0.150	X.XX° ± 0.25°	© THIS DRAWING IS CONFIDENTIAL AND MUST NOT BE COPIED OR DISCLOSED WITHOUT WRITTEN CONSENT	
Third Angle Projection		Scale	Revision
		NTS	E

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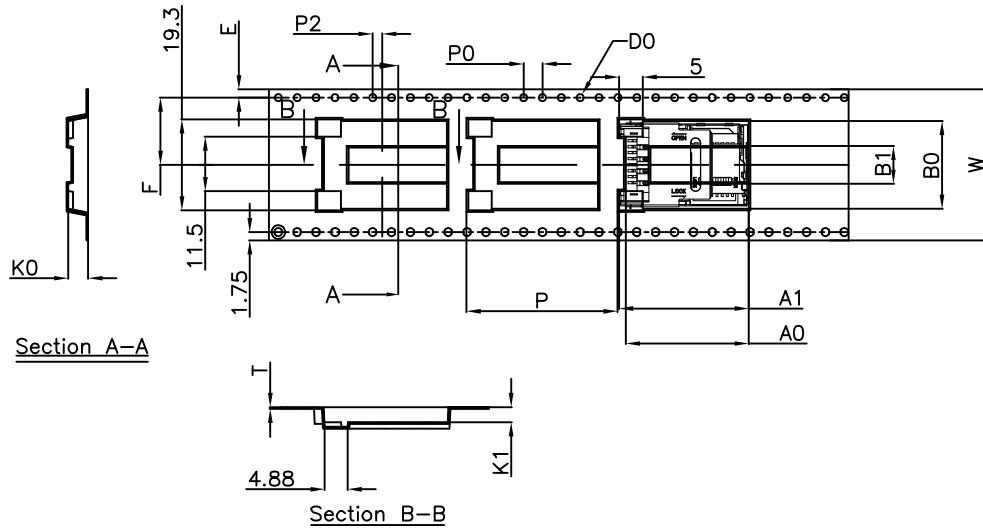
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Scale	Revision	Material	Drawn by	Sheet No.
NTS	E	See Note	PKN	3/5



Notes注意:

- Reserve 200-300mm at the leader & tail of the CARRY TAPE, not to fill any product there. CARRY TAPE 前部分与尾部分各留出 200-300mm 长度不装产品
- Each cavity will hold 1pc. of product. The way of placing the products is as shown in diagram. 每穴放置 1pc 产品, 放置方式如图所示
- After the packing machine filled the REEL, tangle the REEL one more loop with the protection tape, stick on adhesive tape on the four quadrants of the REEL, to avoid spreading out. Stick 1pc. of label on each REEL. 包装机包好后, 再缠上一圈电周波, 在 REEL 的四个登峰造极点贴上胶带, 以预防 REEL 张开, 每 REEL 贴 1PC 标签
- The Packing Method is by Hot-Melting. 包装方式是热熔式
- Firstly put a water-proof bag at the bottom of the cartoon box, then place 1pc. of hard paper card-board on top, following with 1pc. of Bubble Cushioned Pad, and at the four corners, place the triangular pads, then the REEL that filled with products, into the center of the cartoon box. Between the REEL, place 1pc. of Bubble Cushioned Pad as separator, until 5pc. of REEL are filled in the box. Then place 1pc. of Bubble Cushioned Pad & 1pc. of hard paper card board on top, close the cartoon box by plastic tape lastly. 先在纸箱底部套上一防水袋, 再垫上 1pc 硬纸板后再垫上 1pc 气泡垫, 四角垫上三角垫, 然后把装好产品的 REEL 放进纸箱中, 每 REEL 之间隔 1pc 气泡垫, 依次把 5 REEL 产品放到纸箱中, 上面再垫上各 1pc 气泡垫及硬纸板, 最后用胶袋封箱.
- The peel-off force between the COVER TAPE & CARRY TAPE is: 0.1N-0.7N (variation within 0.3N). Peel-off angle: 165-175 degree; Speed of peel-off: 250mm-300mm/min. COVER TAPE 与 CARRY TAPE 剥离力: 0.1N-0.7N (跳动量在 0.3N 以内) 剥离角度: 165-175 度; 剥离速度: 250mm-300mm/分钟



EIA DIMENSIONS	
W	32.0 ^{+0.30} _{-0.30}
E	1.75 ^{+0.10} _{-0.10}
F	14.25 ^{+0.10} _{-0.10}
P	32.0 ^{+0.15} _{-0.15}
P0	4.00 ^{+0.10} _{-0.10}
P2	2.00 ^{+0.10} _{-0.10}
DO	1.50 ^{+0.10} _{-0.10}
T	0.35 ^{+0.05} _{-0.05}
A0	26.10 ^{+0.10} _{-0.10}
A1	27.49 ^{+0.10} _{-0.10}
B0	18.6 ^{+0.10} _{-0.10}
B1	8.00 ^{+0.10} _{-0.10}
K0	4.20 ^{+0.10} _{-0.10}
K1	3.20 ^{+0.10} _{-0.10}

Item	Part Description 品名	Specification 规格	QTY 数量
①	SIM+Micro SD	SIM+Micro SD	350PCS
②	Reel 卷筒	D=Ø330mm, d=Ø100mm, H=44.4mm	5PCS
③	Cover Tape	W=37.5mm, T=0.05mm	75000mm
④	Carry Tape	W=44mm, P=28, T=0.35mm	75000mm
⑤	Hard Cardboard 硬纸板	330mm*330mm*3mm	2PCS
⑥	Bubble-Pad 气泡垫	310mm*10mm	7PCS
⑦	Label 标签		6PCS
⑧	Triangular Pad 三角垫	150mm*133mm*67mm (T=3mm)	4PCS
⑨	Carton Box 纸箱	348mm*348mm*250mm	1PCS
⑩	Water-Proof Bag 防水袋	700mm*700mm*0.5mm	1PCS

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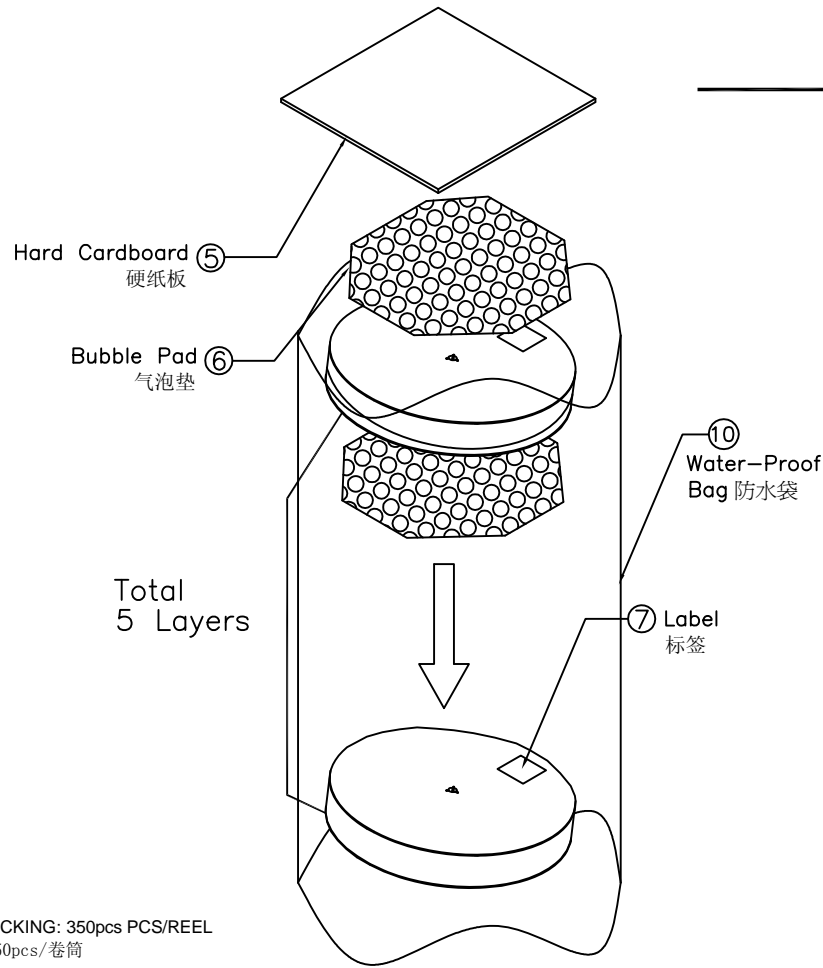


Tolerances (Except as noted)	Part Number:-	Date:-
Dimensions in mm	MES3055	22 MAY 08
	Description:-	
	2 IN 1 COMBO CONNECTOR, MICRO SD MEMORY CARD/SIM CARD, SMT, HINGED, 2.90MM PROFILE, WITH LOCATING POST	
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Scale NTS	Revision E	Material See Note	Drawn by PKN	Sheet No. 4/5
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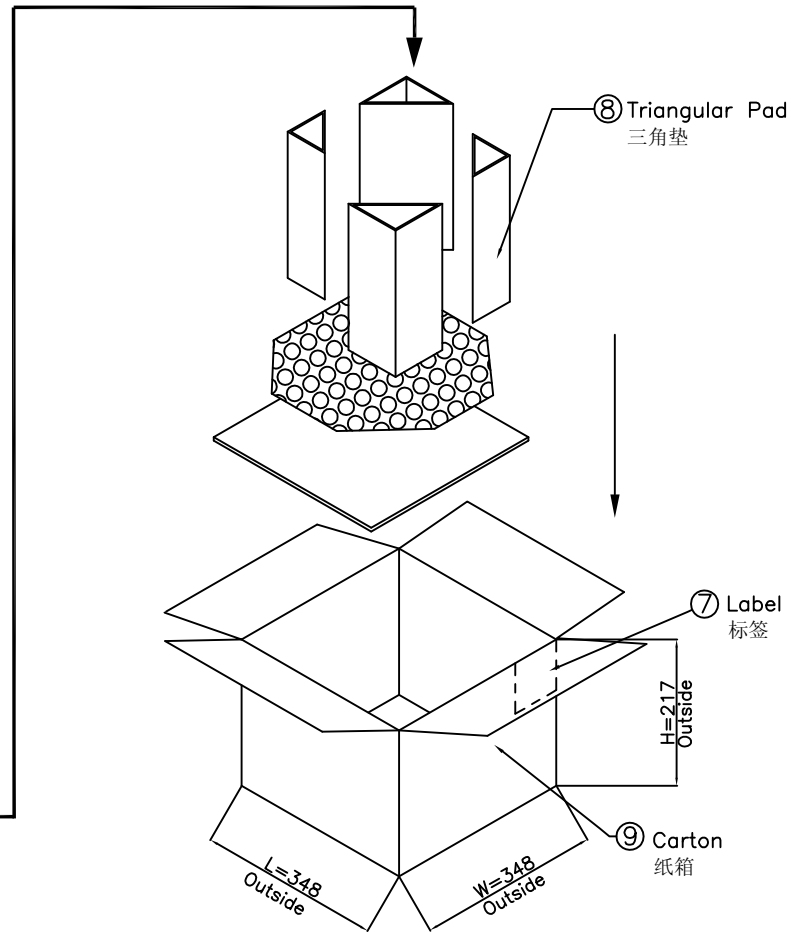
NOTES注意:

1.PRIMARY PACKING: 350pcs PCS/REEL
第一重包装: 350pcs/卷筒

2.SECONDARY PACKING: 5 REELS/CARTON(1750
PCS/CARTON)
第二重包装: 5卷筒/纸箱 (共1750pcs/纸箱)

3.NET WEIGHT:1.08g/PCS,540g/REEL.
净重: 1.08g/pcs, 540g/卷筒

4.GROSS WEIGHT:0.90Kg/REEL,5.3Kg/CARTON.
毛重: 0.9Kg/卷筒, 5.3Kg/纸箱



By	PKN	DMR	ASE	PN	AE
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Tolerances (Except as noted)	Part Number:- MES3055	Date:- 22 MAY 08
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Scale NTS	Revision E	Material See Note	Drawn by PKN	Sheet No. E & OE 5/5
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